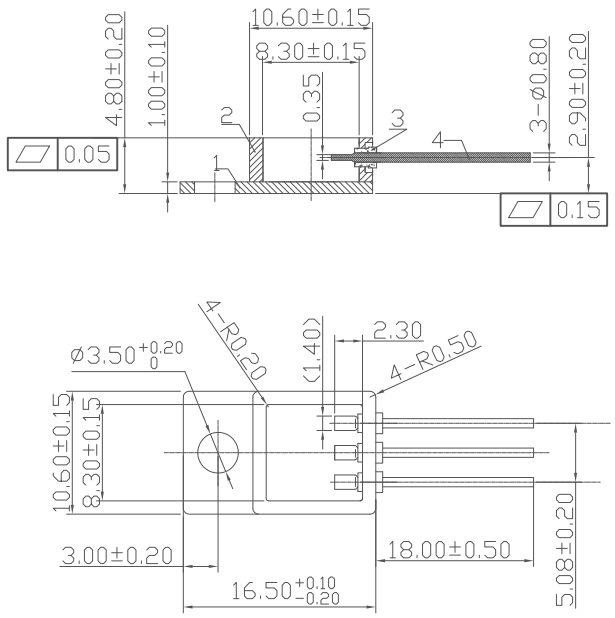
SSM P/N HDR25706

REVISIONS					
REV	ZONE	ECO #	DESCRIPTION	CHANGED BY	DATE
A			INITIAL DESIGN		6/14/08



NOTES:
GENERAL SPECIFICATIONS COMPLY WITH
MIL-STD-750E AND SCREENED PER MIL-PRF-38354

1. MATERIAL: SEE BOM
2. FINAL FINISH:
   2.54 μM ELECTROLESS NICKEL PLATED FOR
   THE ENTIRE PACKAGE SURFACE.
3. PART MUST EQUAL OR EXCEED 10^9 OHMS
   ISOLATION TEST WITH 500 V.D.C PINS TO CASE
4. BREAKDOWN VOLTAGE: PART MUST PASS
   1000V BREAKDOWN VOLTAGE TEST WITH
   NORMAL TESTING CONDITIONS (PINS AND CASE)
5. PART MUST PASS FINE LEAK TEST $1X10^{-8}$
   ATM (HE)/CC/SEC.MAX.

BILL OF MATERIAL		
ITEM	COMPONENT NAME	RAW MATERIAL
1	BASE	OFHC COPPER
2	FRAME	KOVAR/4J29
3	CERAMIC FEEDTHRU	AL203 95%
4	PIN	COPPER CORED KOVAR
TOL. U.O.S	ALL DIMENSIONS ARE IN MM, STANDARD ISO 2768-1 [M] AND CHINA GB/T1804-M	

TITLE	CERAMIC TO257 PACKAGE. CU BASE			DRAWN BY	CHECKED BY	APPROVED BY	SCALE	SHEET
P/N	150-01154-00	REVISION	A	JOHN ZHAO		BEN TONG	1 : 1	1 OF 1

SPECTRUM SEMICONDUCTOR MATERIALS, INC.
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